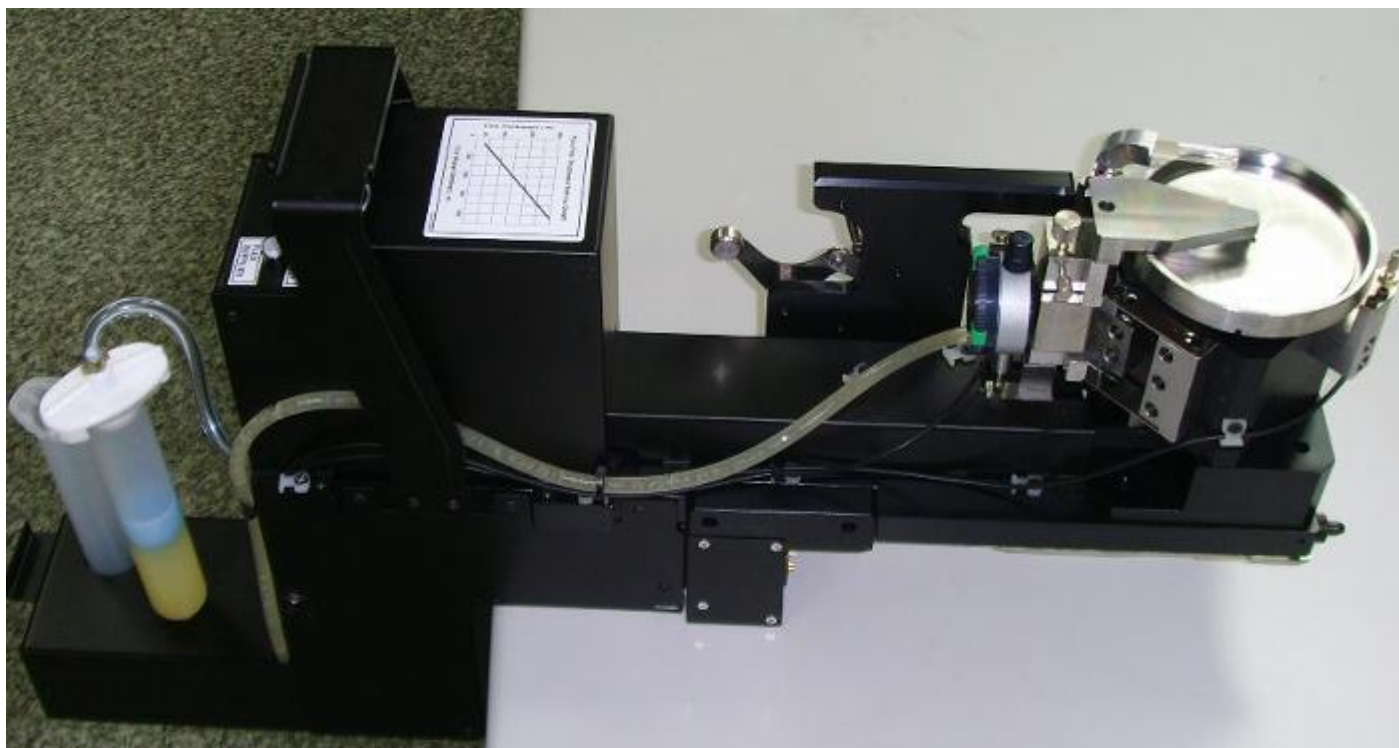




2. 装置外观

● 装置外观



AUTO FLUX DIPPING POP 工程





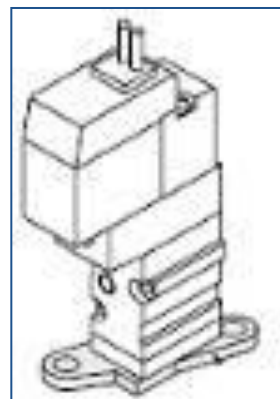
3. 主要机构



电&气 输入部



气量调整开关



3 Port
SOL.VALVE



重量中心



FLUX 管
交换容易



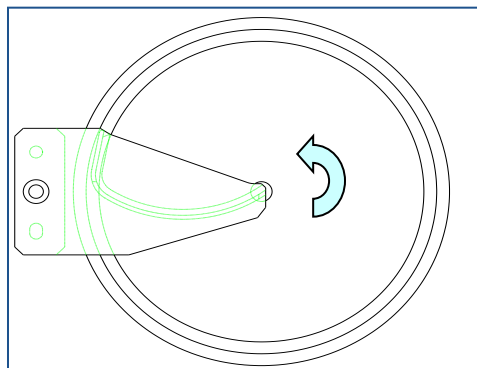
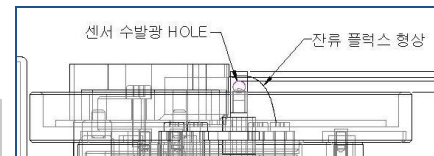
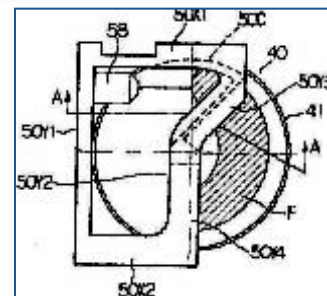
3. 主要机构



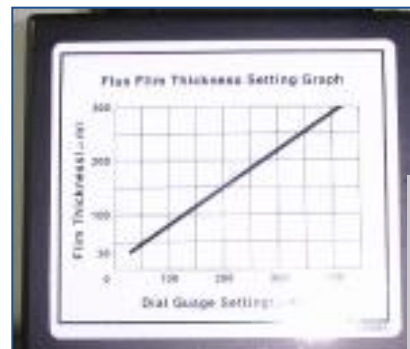
板子弹簧 + 表盘 机构
= **FLUX**厚度调整



脱着性 容易结构
透过性**Sensor**设计



防止**FLUX**溢出
结构



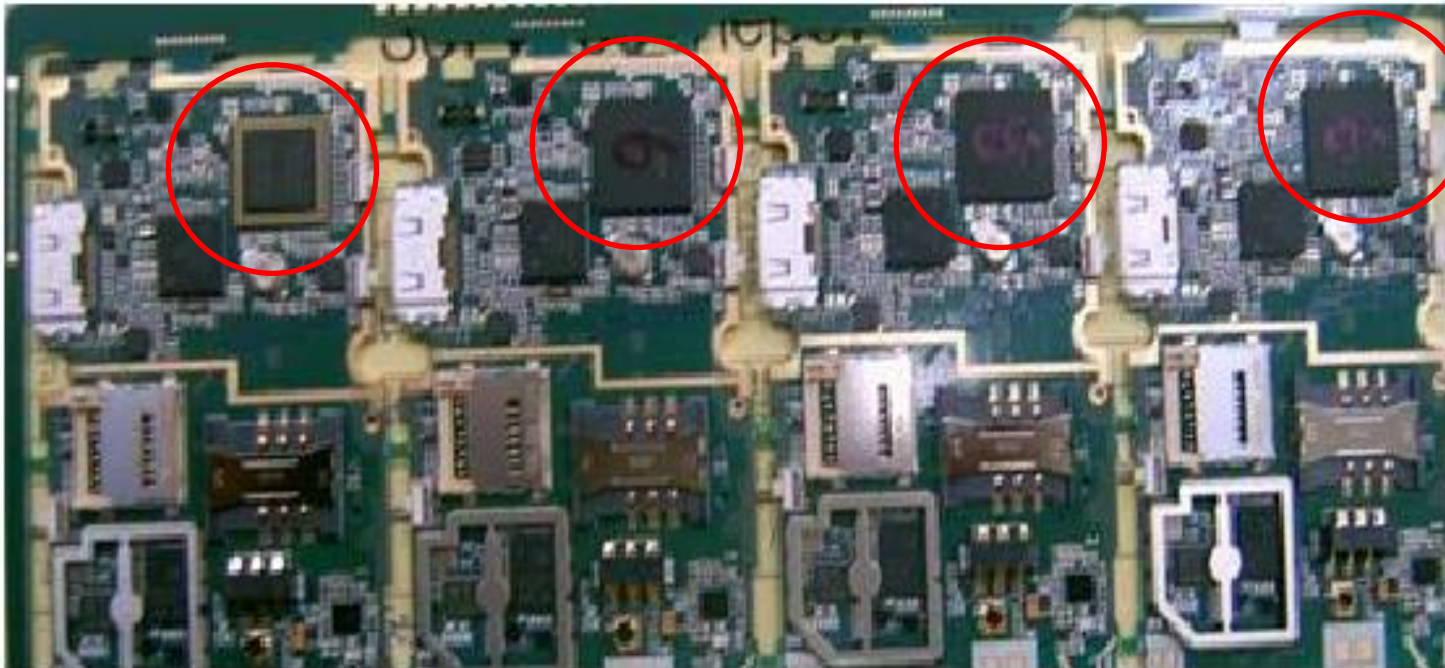
FLUX厚度调整表
FLUX厚度 =
70% X GAP 量



4. Evaluation Test

概要

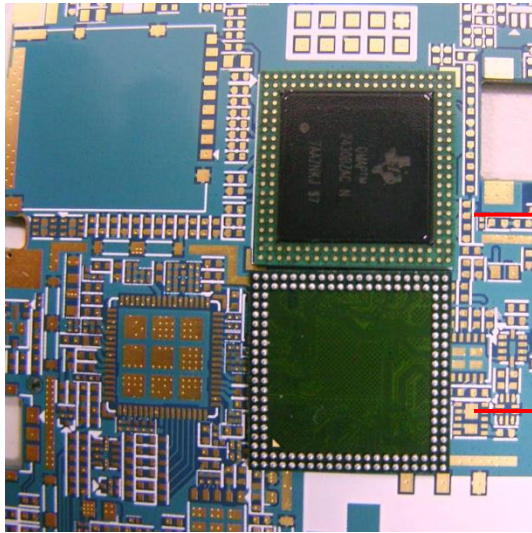
- 公司名 : Q社
- 地方 : 韩国
- 产品 : S社 手机
- PCB : 150mm*110mm x 4Array
- TEST 机器 : SM411F
- TEST 期间 : 2009.2/17~2/27 (总共 11天)





4. Evaluation Test

POP 规格

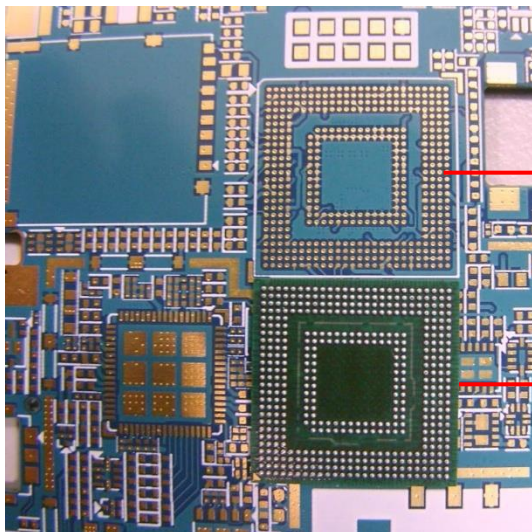


PCB Pattern

BOTTOM PACKAGE

(Bottom Package)

Ball Pitch	Ball Size
0.5	0.35



BOTTOM PACKAGE

TOP PACKAGE

(Top Package)

Ball Pitch	Ball Size
0.65	0.4



4. Evaluation Test

TOP BGA SPEC

1. Part Data

X	14.000	Y	14.000	Thickness	1.000	DepthZ	0.000
---	--------	---	--------	-----------	-------	--------	-------

2. AlignData - Vision Align (BGA)

Camera No. Fix1 Cam Light [S:0:]=[3:3:0]

Size

Body X	14
Body Y	14
Ball Num X	21
Ball Num Y	21
Diameter	0.4
Pitch X	0.65
Pitch Y	0.65
Appear Size	0.500
Align Z	0.000

Option

Grid Type Regular

BGA Flag White

Algorithm Ball

FOV Type

Length

Ball Information

Edit Ball Gap... Miss Balls 1

Uncertainty

Score	Tolerance	Area Margin	Rep. Angle
500	30 %	5	0.000

Direct EX

Bottom BGA SPEC

1. Part Data

X	14.000	Y	14.000	Thickness	0.9	DepthZ	0.000
---	--------	---	--------	-----------	-----	--------	-------

Common Data

3. Show Real Image On

Camera Imagebase OK Cancel

2. AlignData - Vision Align (BGA)

Camera No. Fix1 Cam Light [S:0:]=[3:3:0] Light Test

Size

Body X	14
Body Y	14
Ball Num X	26
Ball Num Y	26
Diameter	0.35
Pitch X	0.5
Pitch Y	0.5
Appear Size	0.500
Align Z	0.000

Option

Grid Type Regular

BGA Flag White

Algorithm Ball

FOV Type None

Length 0.000

Ball Information

Edit Ball Gap... Miss Balls 6

Uncertainty

Score	Tolerance	Area Margin	Rep. Angle
500	30 %	5	0.000

Direction Mark... EX Param...

SWVision(Camera Mode : Fix2 cam)

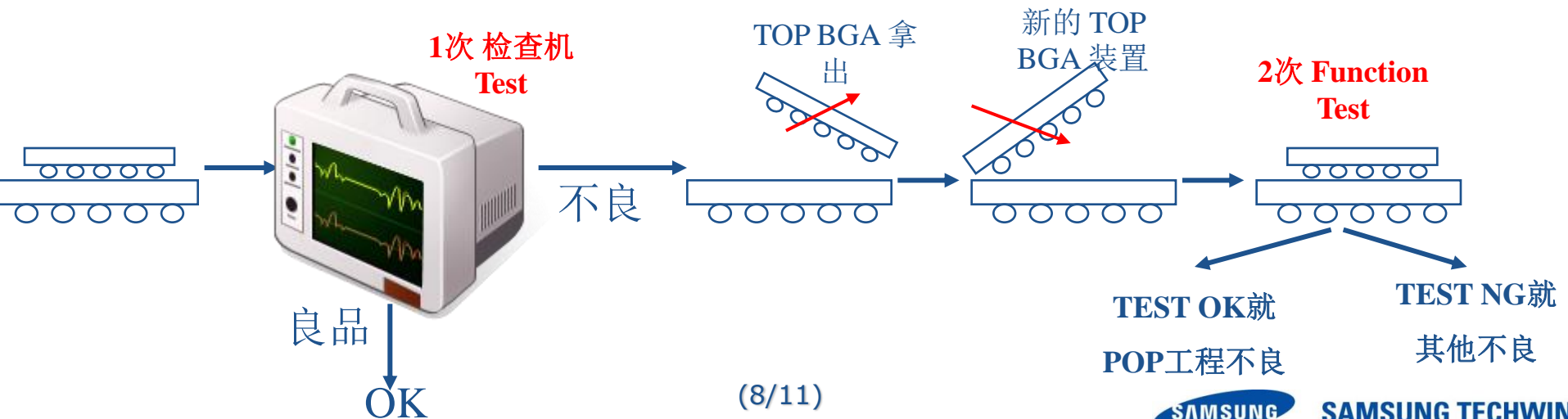
[494, 358]: 28 mag. C2:1x offset



4. Evaluation Test

POP工程不良检查方法

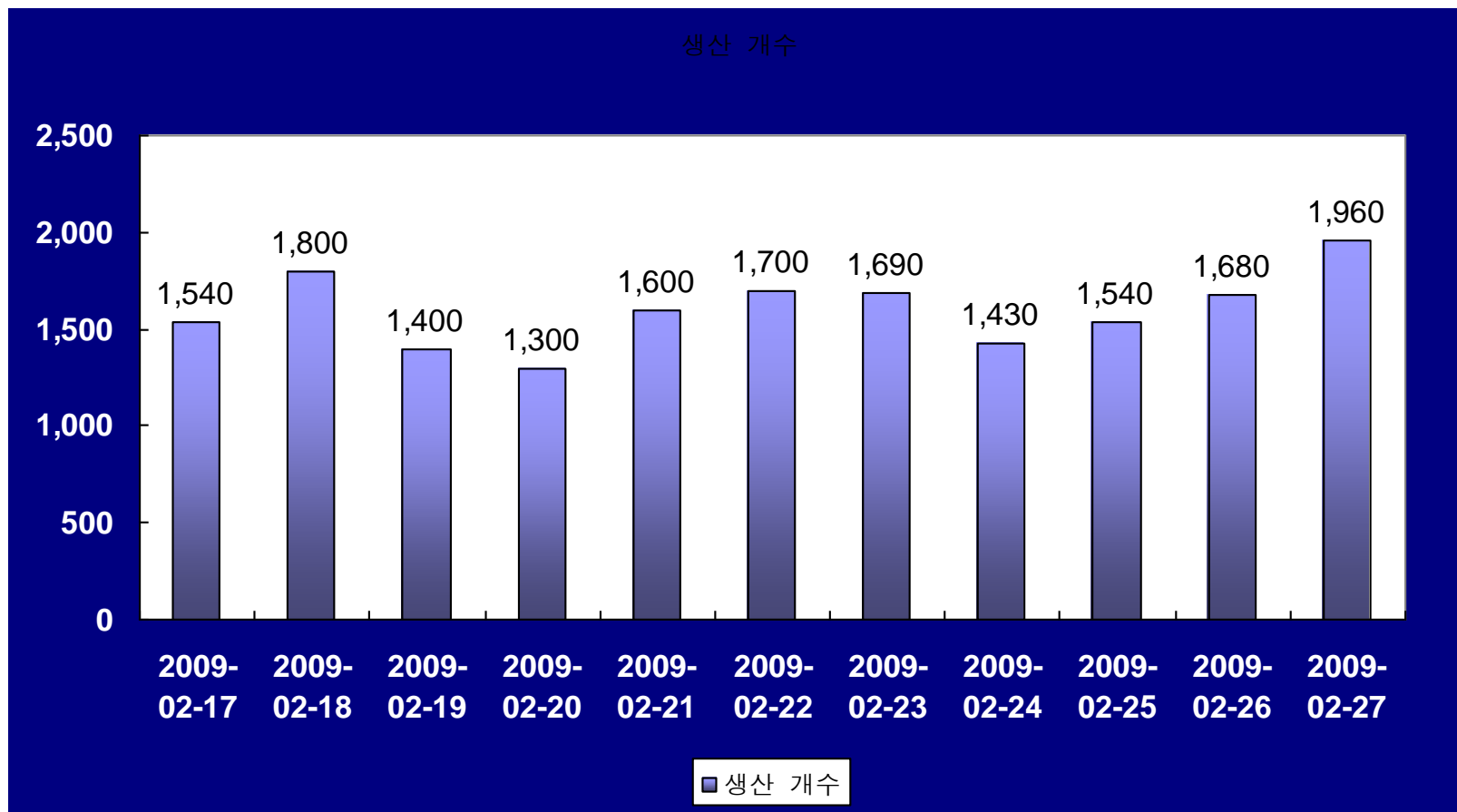
- 1次:使用检查机 FUNCTION TEST
- 2次: 1次Function Test不良时 ,
手动拿出TOP BGA以后装新的BGA, 做2次FUNCTION TEST
 - OK → POP工程不良
 - NG → 其他不良





4. Evaluation Test

测试期间: 2/17~2/27 11天, 总 17,640 PCB 生产





4. Evaluation Test

● 生产结果: **总 17,640个中 不良率 0%**

Date	生产量	1次 Function Test	2次 手动 TEST	备注
2/17	1,540	0	0	
2/18	1,800	4	0	操作人错误
2/19	1,400	0	0	
2/20	1,300	0	0	
2/21	1,600	2	0	原材料 不良
2/22	1,700	0	0	
2/23	1,690	0	0	
2/24	1,430	0	0	
2/25	1,540	2	0	原材料 不良
2/26	1,680	0	0	
2/27	1,960	0	0	
合计	17,640	8	0%	

※ 测试通过后客户买了4台SM411F